

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客 户 : \_\_\_\_\_

PRODUCT 产 品 : \_\_\_\_\_ SAW FILTER \_\_\_\_\_

MODEL NO 型 号 : \_\_\_\_\_ HDF110A W2 \_\_\_\_\_

PREPARED 编 制 : \_\_\_\_\_ CHECKED 审 核 : \_\_\_\_\_

APPROVED 批 准 : \_\_\_\_\_ D A T E 日 期 : \_\_\_\_\_ 2006-5-11 \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子股份有限公司

Shoulder Electronics Limited



## History Record

[illegible]

## 1. SCOPE

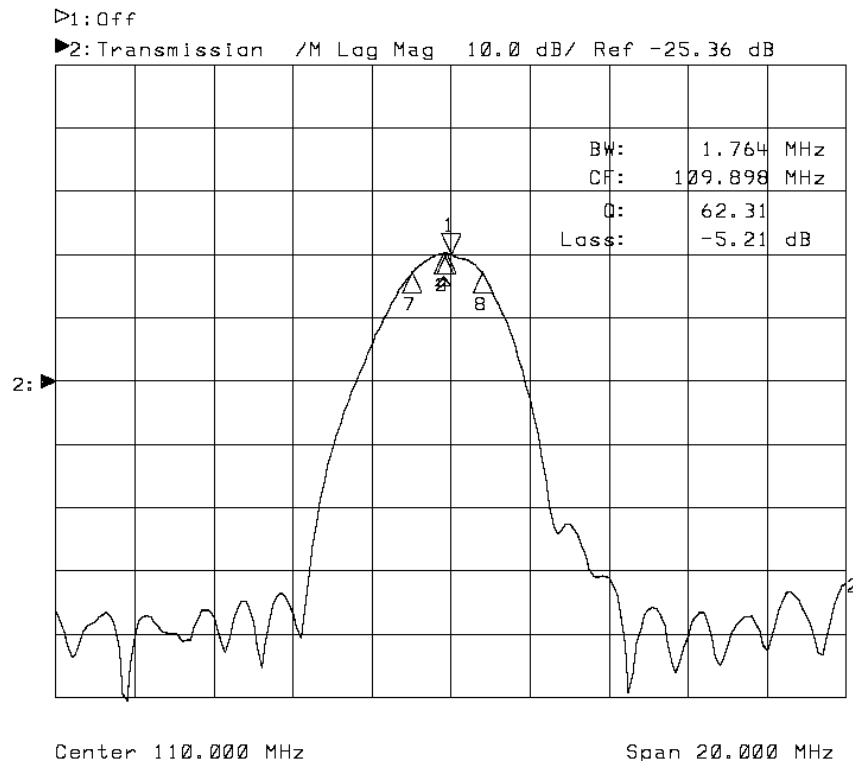
This specification shall cover the characteristics of SAW filter F110A

## 2. ELECTRICAL SPECIFICATION

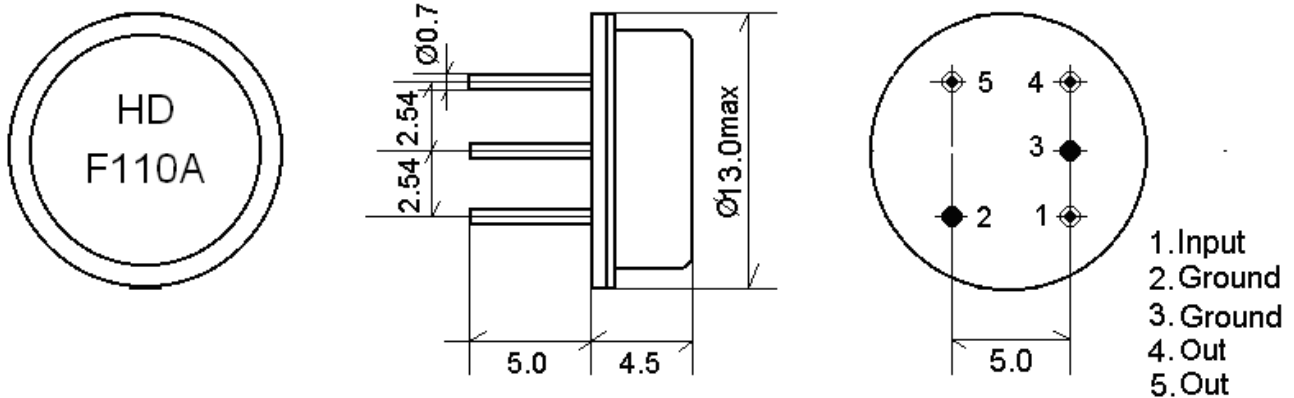
DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-20°C to +55°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

### Electronic Characteristics

型号 Part Number	HDF110A
中心频率(fo)(MHz) Nominal Center Frequency	110.0
3dB 带宽 Bandwidth(from fo)(MHz)	1.6 typ.
阻带衰减 Stop Band Attenuation (from peak level)(dB) 1)fo-5.0MHz 2)fo±3.0MHz 3)fo+5.0MHz	40min 30min 40min
插入损耗(dB) Insertion Loss(at minimum loss point)	6.0max
群延时波动(fo+/-576KHz)(μscc.) Group Delay Deviation	0.200
输入/输出阻抗 Input/output Impedance	50Ω//0pF



### 3. DIMENSION



### 4. ENVIRONMENTAL CHARACTERISTICS

#### 4-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

#### 4-2 Low temperature exposure

Subject the device to -20°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

#### 4-3 Temperature cycling

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+80^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in table 1.

#### 4-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at  $260^{\circ}\text{C} \pm 10^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in table 1.

#### 4-5 Solderability

Subject the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in table 1.

#### 4-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in table 1.

#### 4-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in table 1.

#### 4-8 Lead fatigue

##### 4-8-1 Pulling test

Weight along with the direction of lead without an shock 1kg. The device shall satisfy all the initial Characteristics.

##### 4-8-2 Bending test

Lead shall be subject to withstand against  $90^{\circ}\text{C}$  bending with 450g weight in the direction of thickness. This operation shall be done toward both direction. The device shall show no evidence of damage and shall satisfy all the initial electrical characteristics.

## 5. REMARK

### 5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

